



503.37770X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: M. OGINO, et al.

Serial No.: 09/429,297

Filed: October 28, 1999

For: SEMICONDUCTOR DEVICE, SEMICONDUCTOR WAFER,
SEMICONDUCTOR MODULE, AND A METHOD OF
MANUFACTURING SEMICONDUCTOR DEVICE

Group: 2822

Examiner: James M. Mitchell

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

December 10, 2002

Sir:

In response to the Office Action mailed July 10, 2002, please amend the
above-identified application as follows:

IN THE CLAIMS:

Please amend the claims presently in the application as follows:

02/26/2003 SSURLES 00000005212135 (Twice Amended) A semiconductor device comprising:

01 FC:1202 450.00 CH a semiconductor chip,
a porous stress relaxing layer provided on a plane, whereon circuits
and electrodes are formed, of said semiconductor chip,
a circuit layer provided on said stress relaxing layer and connected to
said electrodes, and

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